

IN THE CLAIMS

Please amend the claims as follows:

1-20. (Canceled)

21. (New) An electronic assembly comprising:

a heat sink that includes an upper surface and a lower surface and an opening extending between the upper and lower surfaces of the heat sink;

a motherboard;

an electronic device between the motherboard and the lower surface of the heat sink;

a pin that engages the upper surface of the heat sink, the pin extending through the opening in the heat sink and the motherboard to couple the heat sink to the electronic device and the motherboard; and

a member within the opening in the heat sink, the member being between the heat sink and the pin.

22. (New) The electronic assembly of claim 21, wherein the member is a bushing that is pressed into the opening in the heat sink.

23. (New) The electronic assembly of claim 22, wherein the pin is pressed through an opening in the bushing.

24. (New) The electronic assembly of claim 21, wherein the member is plastic.

25. (New) The electronic assembly of claim 21, wherein the pin includes a head that is larger than the opening in the heat sink, the head of the pin engaging the upper surface of the heat sink.

26. (New) The electronic assembly of claim 21, further comprising a thermally conductive material between the heat sink and the electronic device.

27. (New) An electronic assembly comprising:
- a heat sink that includes an opening extending through the heat sink;
 - a motherboard;
 - an electronic device between the motherboard and the heat sink;
 - a pin that extends through the opening in the heat sink, the pin being soldered to the motherboard to couple the heat sink to the electronic device and the motherboard; and
 - a member within the opening in the heat sink, the member being between the heat sink and the pin.
28. (New) The electronic assembly of claim 27, wherein the member is a bushing that is pressed into the opening in the heat sink and the pin is pressed through an opening in the bushing.
29. (New) The electronic assembly of claim 27, wherein the heat sink includes an upper surface and a lower surface such that the opening extends between the upper and lower surfaces of the heat sink, the pin engaging the upper surface of the heat sink and the electronic device engaging the lower surface of the heat sink.
30. (New) The electronic assembly of claim 29, wherein the pin includes a head that is larger than the opening in the heat sink, the head of the pin engaging the upper surface of the heat sink.
31. (New) The electronic assembly of claim 27, wherein the pin includes a body that is cylindrical, and the opening in the heat sink is cylindrical.
32. (New) The electronic assembly of claim 27, further comprising a thermally conductive material between the heat sink and the electronic device.

33. (New) A method comprising:
- attaching an electronic device to a motherboard;
 - thermally coupling a heat sink to the electronic device;
 - positioning a member within an opening in the heat sink;
 - inserting a pin through the opening in the heat sink and the motherboard such that the pin engages an upper surface of the heat sink and the member is between the pin and the heat sink;
 - and
 - securing the pin to the motherboard.
34. (New) The method of claim 33, wherein securing the pin to the motherboard includes wave soldering the pin to the motherboard.
35. (New) The method of claim 33, wherein positioning a member within the opening in the heat sink includes pressing a bushing into the opening in the heat sink.
36. (New) The method of claim 33, wherein positioning a member within the opening in the heat sink includes positioning the entire member within the opening in the heat sink.
37. (New) The method of claim 33, wherein positioning a member within the opening in the heat sink includes placing a member that is more elastic than the pin and the heat sink between the pin and the heat sink to alleviate stress between the pin and heat sink.

38. (New) A computer system comprising:

a heat sink that includes an upper surface and a lower surface and an opening extending between the upper and lower surfaces of the heat sink;

a motherboard;

an electronic device between the motherboard and the lower surface of the heat sink;

a pin that engages the upper surface of the heat sink, the pin extending through the opening in the heat sink and the motherboard to couple the heat sink to the electronic device and the motherboard;

a member within the opening in the heat sink, the member being between the heat sink and the pin; and

a chassis, the motherboard being attached to the chassis.

39. (New) The computer system of claim 38, wherein the member is a bushing that is pressed into the opening in the heat sink.

40. (New) The computer system of claim 38, wherein the pin is soldered to the motherboard.